



07-19-2002



102161439

tty. Docket No. JP920010005US1

SHEET

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## 1. Name of conveying party(ies):

Sumio Morioka  
Yasunao Katayama  
Toshiyuki Yamane

6-3-02

Additional name(s) of conveying  
party(ies) attached? \_\_\_ Yes X No

## 2. Name and address of receiving party(ies):

Name: International Business  
Machines Corporation  
Address: New Orchard Road  
Armonk, NY 10504

Additional name(s) & addresses  
attached? \_\_\_ Yes X No

## 3. Nature of conveyance:

X Assignment

Execution Date(s): April 25, 2002, April  
26, 2002, April 26, 2002

## 4. Patent Application number(s)

10/091,774

Execution Date(s): April 25, 2002, April  
26, 2002, April 26, 2002

## 5. Name and address of party to whom correspondence concerning document should be mailed:

Name: Paul J. Otterstedt  
Address: IBM Corporation  
Intellectual Property Law Dept.  
P.O. Box 218  
Yorktown Heights, NY 10598

## 6. Total number of applications involved: 1

## 7. Total fee (37 CFR 3.41): \$40.00

X Charge to Deposit Account No.:  
09-0468

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## 8. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of original document.

Paul J. Otterstedt (Reg. No. 37,411)

Name of Person Signing

Signature

May 21, 2002

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07/18/2002 DBYRNE 00000193 090468 10091774

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PATENT

REEL: 013087 FRAME: 0919

# Assignment

Whereas, we

INVENTOR  
AND CITY

(1) Sumio Morioka  
Yamato-shi, Kanagawa-ken

4182-2-407 Shimotsuruma  
Japan

INVENTOR  
AND CITY

(2) Yasunao Katayama  
Hachiouji-shi, Tokyo

6-17-8 Minamino  
Japan

INVENTOR  
AND CITY

(3) Toshiyuki Yamane  
Yamato-shi, Kanagawa-ken

Seline-406 5-6-8 Chuorinkan  
Japan

have invented certain improvements in

TITLE COMBINATIONAL CIRCUIT, AND ENCODER, DECODER AND SEMICONDUCTOR  
DEVICE USING THIS COMBINATIONAL CIRCUIT

and executed, respectively, a United States patent application therefor on

DATES THAT  
INVENTORS  
SIGNED THE  
DECLARATION

(1) April 25, 2002, and (2) April 26, 2002,  
(3) April 26, 2002,

Whereas, INTERNATIONAL BUSINESS MACHINES CORPORATION, a corporation of New York, having a place of business at Armonk, New York 10504, (hereinafter called IBM), desires to acquire the entire right, title and interest in the said application and invention, and to any United States and foreign patents to be obtained therefor;

Now therefore, for a valuable consideration, receipt whereof is hereby acknowledged, we, the above named, hereby sell, assign, and transfer to IBM, its successors and assigns, the entire right, title and interest in the said application and invention therein disclosed for the United States and foreign countries, and all rights of priority resulting from the filing of said United States application, and we request the Commissioner of Patents to issue any Letters Patent granted upon the inventions set forth in said applications to IBM, its successors and assigns; and we hereby agree that IBM may apply for foreign Letters Patent on said invention and we will execute all papers necessary in connection with the United States and foreign applications when called upon to do so by IBM.

Signed and sealed

CITY AND  
DATE

(1) at Yamato  
on April 25, 2002,

Sumio Morioka

SIGNATURE

( Sumio

Morioka ) INVENTOR

FIRST NAME

MIDDLE INITIAL

LAST NAME